

TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	Integrated Circuit Chip Having A Ringed Wiring Layer Interposed Between A Contact Layer And A Wiring Grid	
Application Number :		
Date :		
First Named Applicant:	Thomas R. Bednar	
Confirmation Number:		
Attorney Docket Number:	BUR920020107US1	
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Submitted By:		Elec. Sign.
Richard A. Henkler Registered Number: 39,220		Richard A. Henkler / s /
		Sign. Capacity Attorney

Documents being submitted:	Files
us-ids	BUR920020107US1-usidst.xml us-ids.dtd us-ids.xsl
us-assignment	BUR920020107US1-usassn.xml us-assignment.xsl us-assignment.dtd BUR920020107US1assign1.tif BUR920020107US1assign2.tif BUR920020107US1assign3.tif
us-request	BUR920020107US1-usrequ.xml us-request.dtd us-request.xsl
us-fee-sheet	BUR920020107US1-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
us-declaration	BUR920020107US1dec1.tif
us-declaration	BUR920020107US1dec2.tif
us-declaration	BUR920020107US1dec3.tif
us-declaration	BUR920020107US1dec4.tif
us-declaration	BUR920020107US1dec5.tif
application-body	BUR920020107spec-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd BUR920020107drw1.tif

BUR920020107drw2.tif
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Comments

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